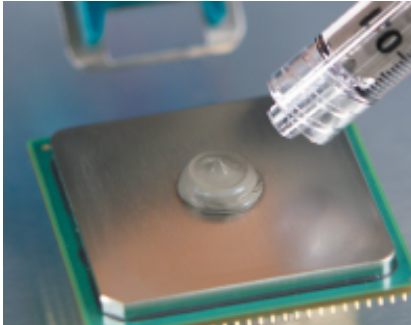


High Performance, Value Compound for High-End Computer Processors

## Features and Benefits

- High thermal performance: 0.32°C/W (TO-220 thermal test @ 50 psi)
- Good screenability
- Room temperature storage
- No post “cure” required
- Exceptional value



TIC 1000A is a high performance, thermally conductive compound intended for use as a thermal interface material between a high end computer or graphic processor and a heat sink. Other high watt density applications will also benefit from the extremely low thermal impedance of TIC 1000A.

TIC 1000A compound wets-out the thermal interface surfaces and flows to produce the lowest thermal impedance. The compound requires pressure of the assembly to cause flow. The TIC 1000A compound will resist dripping.

For microprocessor applications, traditional screw fastening or spring clamping methods will provide adequate force to optimize the thermal performance of TIC 1000A.

An optimized application would utilize the minimum volume of TIC 1000A material necessary to ensure complete wet-out of both mechanical interfaces.

### Assembly – No Post Screen Cure

TIC 1000A has good screenability. No solvent is used to reduce the viscosity, so no post “cure” conditioning is required.

TYPICAL PROPERTIES OF TIC 1000A						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Gray	Gray	Visual			
Density (g/cc)	2.1	2.1	ASTM D792			
Continuous Use Temp (°F) / (°C)	302	150	—			
<b>ELECTRICAL</b>						
Electrical Resistivity (Ohm-meter) (1)	N/A	N/A	ASTM D257			
<b>THERMAL</b>						
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470			
<b>THERMAL PERFORMANCE vs PRESSURE</b>						
	Pressure (psi)	10	25	50	100	200
	TO-220 Thermal Performance (°C/W) (2)	0.32	0.32	0.32	0.31	0.28

1) The compound contains an electrically conductive filler surrounded by electrically non-conductive resin.  
2) TO-220 performance data is provided as a reference to compare material thermal performance.

### Application Cleanliness

It is recommended to pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TIC 1000A.

### Application Methods

1. Dispense and/or screen print TIC 1000A compound onto the processor or heat sink surface like thermal grease (see a Bergquist Representative for application information).
2. Assemble the processor and heat sink with spring clips or constant-pressure fasteners.

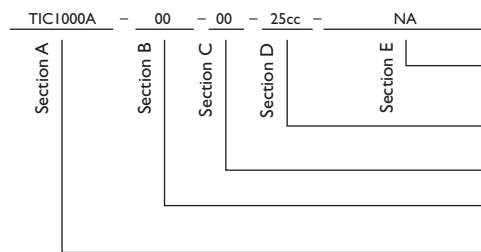
## Typical Applications Include:

- High performance CPUs
- High performance GPUs

## Configurations Available:

- **Custom Configuration** - TIC 1000A is available in a gel form (TIG); TIG 1000A requires storage below 10°C and is a room-temperature cure.

## Building a Part Number



## Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Cartridges: 5cc = 5.0cc, 25cc = 25.0cc, 200cc = 200.0cc, 800cc = 800.0cc, 1600cc = 1600.0cc

00 = No options

00 = No options

TIC1000A = Thermal Interface Compound 1000A  
TIG1000A = Thermal Interface Gel 1000A

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).



[www.bergquistcompany.com](http://www.bergquistcompany.com)

The Bergquist Company -  
North American Headquarters  
18930 West 78th Street  
Chanhassen, MN 55317  
Phone: 800-347-4572  
Fax: 952-835-0430

The Bergquist Company -  
European Headquarters  
Bramenberg 9a, 3755 BT Eemnes  
Netherlands  
Phone: 31-35-5380684  
Fax: 31-35-5380295

The Bergquist Company -  
Asian Headquarters  
4th Floor, Number 10, Lane 80  
Kuang-Fu South Road  
Taipei, Taiwan ROC 106  
Ph: 886-2-2778-1048  
Fax: 886-2-2778-1049

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